

| | Title | Current OR |
|----------|--|-------------------|
| 1 | Method of making laminar stackable circuit board structure | 29/852 |
| 2 | Product for surface mount solder joints | 428/601 |
| 3 | Method of fabricating a multi-layer integrated circuit chip interposer | 29/852 |
| 4 | Method for replacing IC chip package interposer | 29/830 |
| 5 | Process for fabricating microwave and millimeter wave stripline filters | 29/830 |
| 6 | Process for preparing multi-layer printed wiring board | 29/830 |
| 7 | Metal transfer layers for parallel processing | 29/830 |
| 8 | Method of making rigid-flexible multilayer board system | 29/830 |

| | Current XRef |
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| 1 | 174/266; 257/E23.172; 428/901 |
| 2 | 174/261; 428/687 |
| 3 | 216/18; 216/20; 257/E23.067; 257/E23.171; 29/830 |
| 4 | 257/E23.067; 257/E23.171; 29/402.06; 29/402.08; 29/831 |
| 5 | 156/89.12; 156/89.14; 156/89.15; 156/89.17; 156/89.18; 333/204; 333/238; 430/314 |
| 6 | 216/20; 216/67 |
| 7 | 174/262; 216/17; 216/33; 257/E23.173; 29/846; 428/901 |
| 8 | 228/180.1; 228/180.21; 29/840; 439/44; 439/47; 439/48; 439/67 |

| | Title | Current OR |
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| 9 | Method of manufacturing multilayered printed-wiring-board | 29/830 |
| 10 | Multilayer circuit board fabricated from silicon | 333/238 |

| | Current XRef |
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| 9 | 174/259; 228/111.5; 228/175; 29/840; 361/776; 361/804 |
| 10 | 228/180.22; 29/830; 361/792; 428/450; 428/901 |